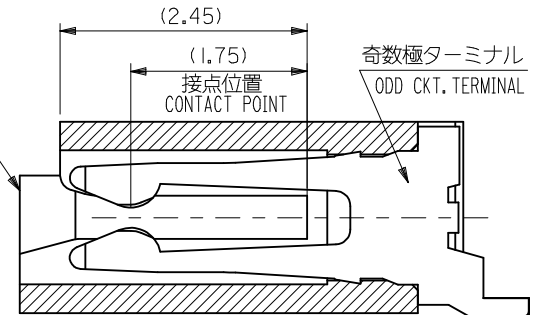
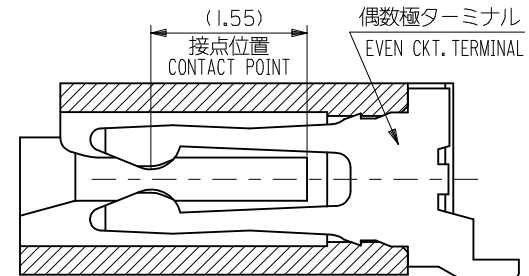


ハウジング
HOUSING



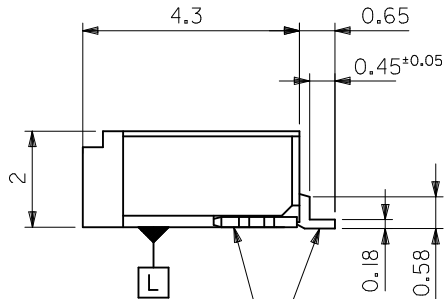
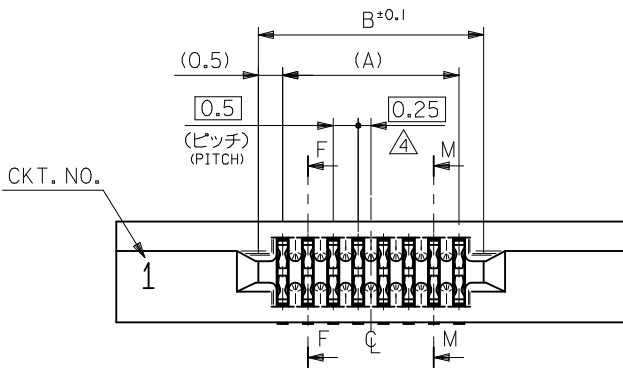
SECT. M-M

SCALE 20:1



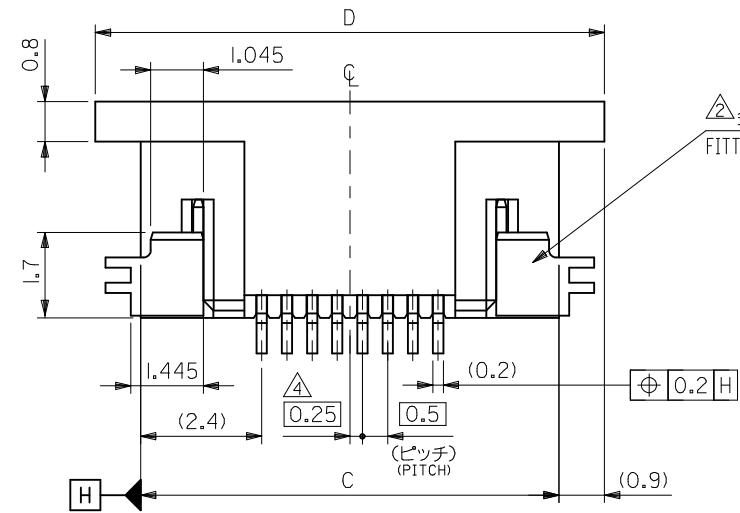
SECT. F-F

SCALE 20:1

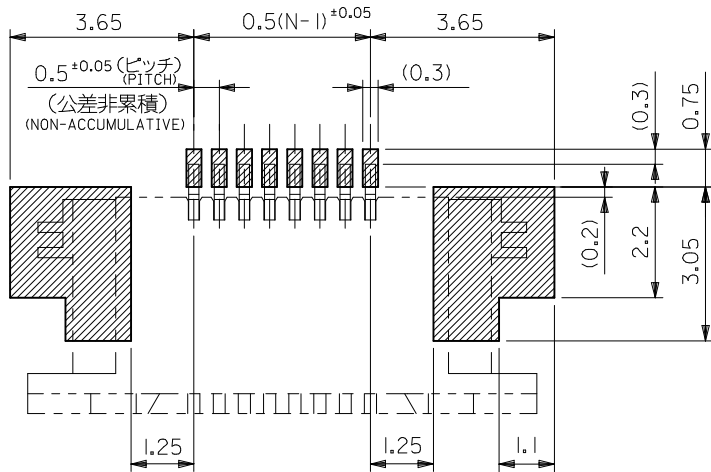


注記(NOTES)

1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅、ニッケル下地 金メッキ (接点部)、錫メッキ (テール部)
(PHOSPHOR BRONZE t=0.2, GOLD (CONTACT), TIN (TAIL) PLATING OVER NICKEL)
ハウジング (HOUSING): 46ナイロン(46NYLON), UL94V-0
金具 (FITTING NAIL): リン青銅、ニッケル下地、錫メッキ
(PHOSPHOR BRONZE t=0.2, TIN PLATING OVER NICKEL)
- △ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
- △ ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 \square に対し上方向 0.1MAX.、下方向 0.15MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM \square .
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
- △ 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
5. 本製品は 52689-**40 の鉛フリー (部分金メッキ) 品である。
THIS PRODUCT IS LEAD FREE OF 52689-**40 (CONTACT GOLD PLATING).

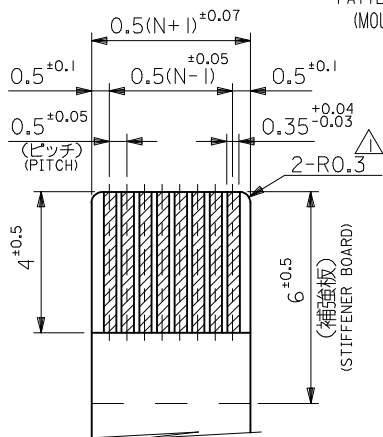


REVISED EC NO: J2016-0905 DRWN: YMIZUNO02 2016/02/24 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	± 0.03	DRAWN BY M. NABE I	DATE '04/08/06	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-	
	0.25 OVER	0.5 UNDER	± 0.05	CHECKED BY K. TOJO	DATE '04/08/06		
	0.5 OVER	1.0 UNDER	± 0.1	APPROVED BY N. UKITA	DATE '04/08/06		
1.0 OVER	10 UNDER	± 0.2	MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-52689-040	SHEET NO. 1 OF 2	
10 OVER	30 UNDER	± 0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		± 0.3	SIZE A3				



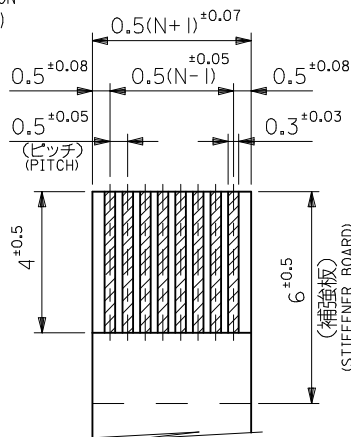
参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

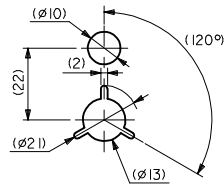
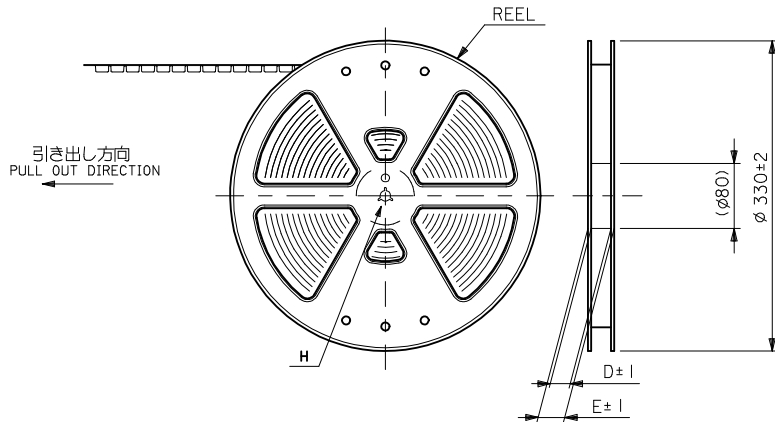
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

52689-**-66	17.6	21.1	19.3	15.5	14.5	52689-3075	52689-3066	30
	14.6	18.1	16.3	12.5	11.5	52689-2475	52689-2466	24
	13.1	16.6	14.8	11.0	10.0	52689-2175	52689-2166	21
MODEL NO.	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
	ORDER No. オーダー番号							

REVISED EC NO: J2016-0905 DRWN: YIMZUN02 2016/02/24 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER	UNDER	±0.03	DRAWN BY MNABEI	DATE '04/08/06	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY KTOJO	DATE '04/08/06				
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE '04/08/06				
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.		
	10 OVER	30 UNDER	±0.25	SEE TABLE		SD-52689-040	2 OF 2		
	30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
	ANGULAR	±3 °							
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								
	REV								

注記 NOTES

- 製品詳細寸法については図面 SD-52689-040 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-040.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



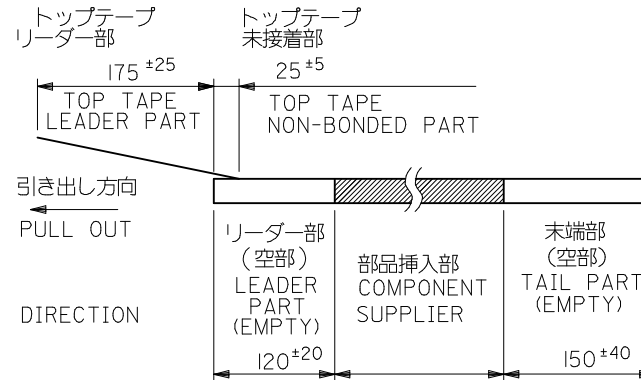
DETAIL H

5. 材料 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS)

MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYRENE

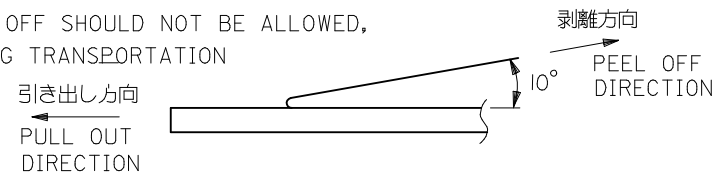
6. 本製品は 52689-**97 の鉛フリー(部分金メッキ)品である。
 THIS PRODUCT IS LEAD FREE OF 52689-**97 (CONTACT GOLD PLATING).

7. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
 THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

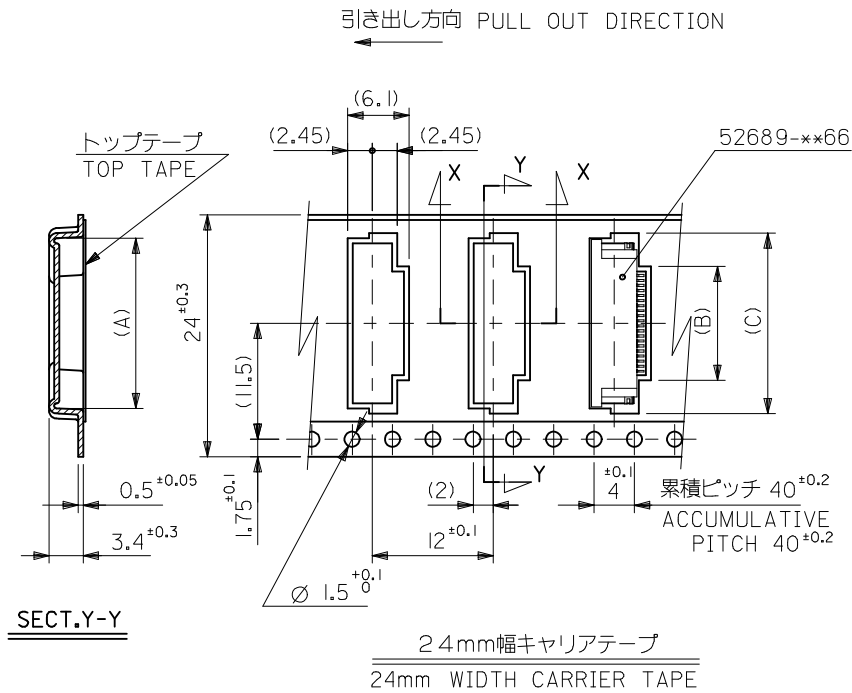


- トップテープの剥離強度：(剥離方向は下図参照)
 0.1~1.3N {10~130gf} 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
 0.1~1.3N {10~130gf}(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION

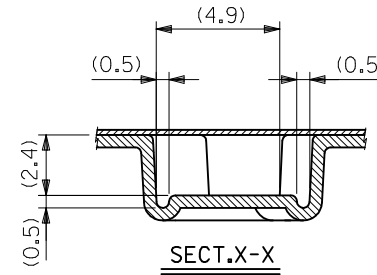
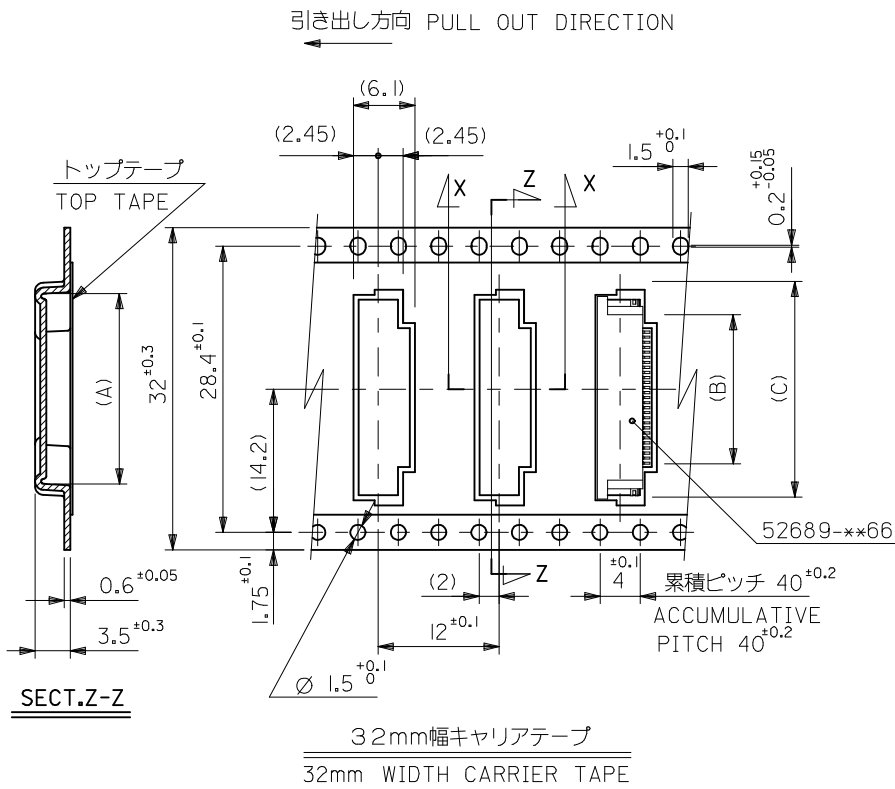


REVISED EC NO: J2016-0905 DRWN:YMIZUNO02 2016/02/24 CHKD:KATAHASHI 2016/02/29 APPR:IKUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	52689-**75	MODEL NO.
	0.25 UNDER	UNDER	±0.03	DRAWN BY MNABEI	DATE '04/08/06	DESIGN UNITS METRIC	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY KTOJO	DATE '04/08/06	THIRD ANGLE PROJECTION	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE '04/08/06	TITLE EMBOSSD TAPE PACKAGE FOR 52689-**66 -LEAD FREE-	
1.0 OVER	30 UNDER	±---	MATERIAL NO.	DOCUMENT NO.	SD-52689-041		SHEET NO. 1 OF 3
30 OVER		±---	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR	±--- °						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



24	29.4	25.4	17.9	11.3	16.9	52689-2175	21
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MAIERIAL NO.	CIRCUIT

REVISED EC NO: J2016-0905 DRWN: YMIZUNO02 2016/02/24 CHKD: KTAHAKASHI 2016/02/29 APPR: IKUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY MNABEI	DATE '04/08/06	TITLE EMBOSSD TAPE PACKAGE FOR 52689-**66 -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY KTOJO	DATE '04/08/06		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE '04/08/06		
	1.0 OVER	10 UNDER	±---	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-52689-041	SHEET NO. 2 OF 3	
10 OVER	30 UNDER	±---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±---	SIZE A3				
ANGULAR	±---	°					



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

32	37.4	33.4	22.4	15.8	21.4	52689-3075	30
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	52689-2475	24
						MATERIAL NO.	CIRCUIT

REVISED EC NO: J2016-0905 DRWN: YIMZUN02 2016/02/24 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
	0.25 UNDER UNDER ±0.03		MM ONLY		---		METRIC		<input checked="" type="checkbox"/> THIRD ANGLE <input type="checkbox"/> FIRST ANGLE	
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY		DATE		TITLE		EMBOSSED TAPE PACKAGE	
	0.5 OVER 1.0 UNDER ±0.1		MNABEI		'04/08/06		FOR 52689-**66		-LEAD FREE-	
	1.0 OVER 10 UNDER ±---		CHECKED BY		DATE		molex		MATERIAL NO.	
10 OVER 30 UNDER ±---		KTOJO		'04/08/06		SD-52689-041		SHEET NO.		
30 OVER ±---		APPROVED BY		DATE		SEE TABLE		3 OF 3		
ANGULAR ±--- °		NUKITA		'04/08/06		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.						
		SIZE		A3						